

MM9BZ2V2B~MM9BZ39B-HAF

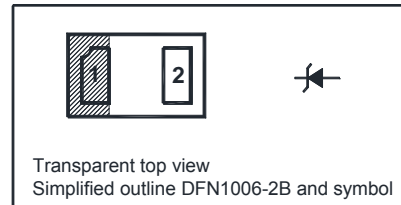
Silicon Planar Zener Diodes

Features

- Total power dissipation: max. 250 mW
- Small plastic package suitable for surface mounted design
- High reliability
- Halogen and Antimony Free(HAF), RoHS compliant

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Power Dissipation	P_{tot}	250	mW
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{Stg}	- 55 to + 150	$^\circ\text{C}$

Characteristics at $T_a = 25^\circ\text{C}$

Parameter	Symbol	Max.	Unit
Forward Voltage at $I_F = 10 \text{ mA}$	V_F	0.9	V

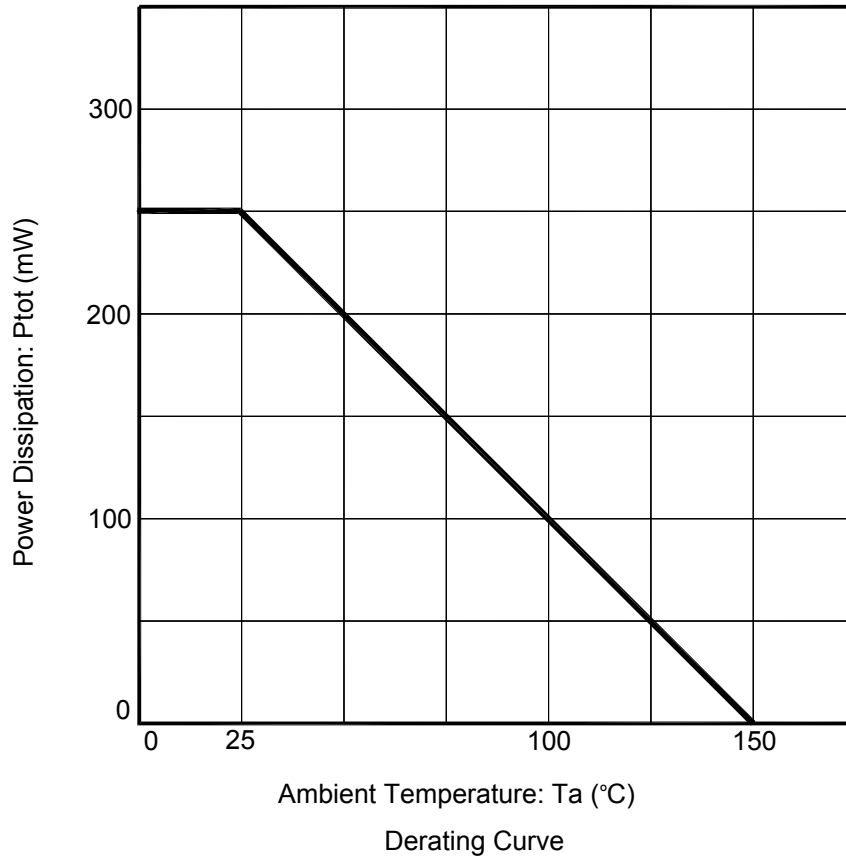
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Characteristics at $T_a = 25^\circ\text{C}$

Type	Marking Code	Zener Voltage ¹⁾			Dynamic Resistance		Leakage Current	
		V_{ZT}		at I_{ZT}	Z_{ZT}	at I_{ZT}	I_R	at V_R
		Min. (V)	Max. (V)	(mA)	Max. (Ω)	(mA)	Max. (μA)	(V)
MM9BZ2V2B	8A	2.1	2.4	5	100	5	120	0.7
MM9BZ2V4B	8B	2.3	2.65	5	100	5	120	1
MM9BZ2V7B	8C	2.65	2.95	5	110	5	120	1
MM9BZ3V0B	8D	2.95	3.25	5	120	5	50	1
MM9BZ3V3B	8E	3.25	3.55	5	120	5	20	1
MM9BZ3V6B	8F	3.6	3.845	5	100	5	10	1
MM9BZ3V9B	8G	3.89	4.16	5	100	5	5	1
MM9BZ4V3B	8H	4.17	4.43	5	100	5	5	1
MM9BZ4V7B	8J	4.55	4.75	5	100	5	2	1
MM9BZ5V1B	8K	4.98	5.2	5	80	5	2	1.5
MM9BZ5V6B	8L	5.49	5.73	5	60	5	1	2.5
MM9BZ6V2B	8M	6.06	6.33	5	60	5	1	3
MM9BZ6V8B	8N	6.65	6.93	5	40	5	0.5	3.5
MM9BZ7V5B	8P	7.28	7.6	5	30	5	0.5	4
MM9BZ8V2B	8Q	8.02	8.36	5	30	5	0.5	5
MM9BZ9V1B	8R	8.85	9.23	5	30	5	0.5	6
MM9BZ10B	8S	9.77	10.21	5	30	5	0.1	7
MM9BZ11B	8T	10.76	11.22	5	30	5	0.1	8
MM9BZ12B	8U	11.74	12.24	5	30	5	0.1	9
MM9BZ13B	8V	12.91	13.49	5	37	5	0.1	10
MM9BZ15B	8W	14.34	14.98	5	42	5	0.1	11
MM9BZ16B	8X	15.85	16.51	5	50	5	0.1	12
MM9BZ18B	8Y	17.56	18.35	5	65	5	0.1	13
MM9BZ20B	8Z	19.52	20.39	5	85	5	0.1	15
MM9BZ22B	9A	21.54	22.47	5	100	5	0.1	17
MM9BZ24B	9B	23.72	24.78	5	120	5	0.1	19
MM9BZ27B	9C	26.19	27.53	5	150	5	0.1	21
MM9BZ30B	9D	29.19	30.69	5	200	5	0.1	23
MM9BZ33B	9E	32.15	33.79	5	250	5	0.1	25
MM9BZ36B	9F	35.07	36.87	5	300	5	0.1	27
MM9BZ39B	9G	37	41	5	100	5	2	30

¹⁾ V_{ZT} is tested with pulses (20 ms).

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TOP DYNAMIC

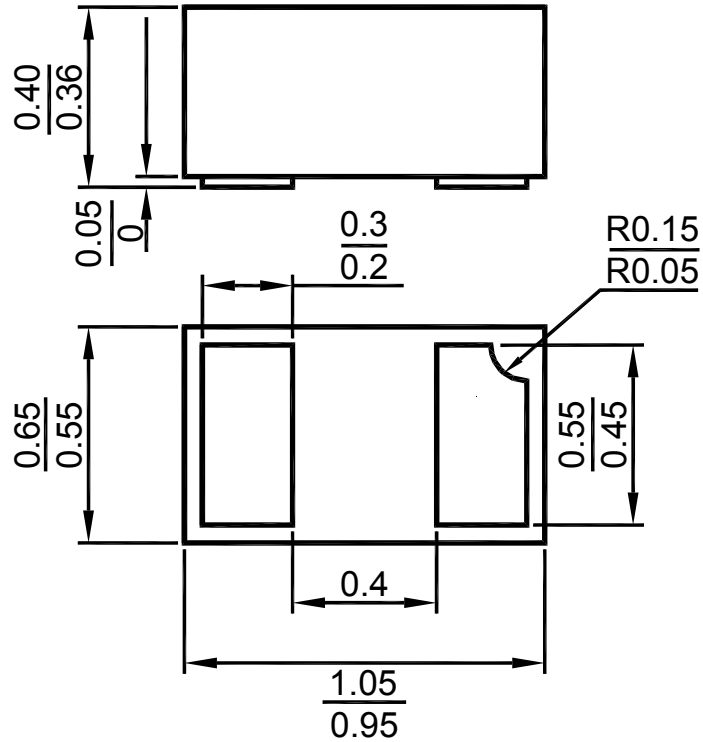
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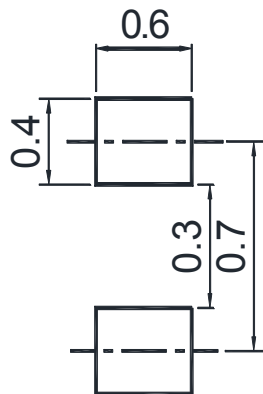
PACKAGE OUTLINE

Plastic surface mounted package

DFN1006-2B



Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
DFN1006-2B	8	4 ± 0.1	0.157 ± 0.004	178	7	5,000

TOP DYNAMIC

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